

INTERNATIONAL STANDARD

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**Mechanical standardization of semiconductor devices –
Part 6-10:
General rules for the preparation of outline drawings of
surface mounted semiconductor device packages –
Dimensions of P-VSON**

*Normalisation mécanique des dispositifs à semiconducteurs –
Partie 6-10:
Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
pour montage en surface –
Dimensions des boîtiers P-VSON*

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Dimensions of P-VSON

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International Standard IEC 60191-6-10 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/551/FDIS	47D565/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

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1 Scope

This part of IEC 60191 provides the common outline drawings and dimensions for all types of structures and composed materials of plastic very thin small outline non-lead package (hereinafter called P-VSON).

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60191(all parts), *Mechanical standardization of semiconductor devices*

ISO/DIS 2692: *Geometrical Product Specification (GPS) – Geometrical tolerancing – Maximum material requirement (MMR) and least material requirement (LMR)*.